

Single N-Channel MOSFET

■ DESCRIPTION

SMC2302 is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss are needed in small outline surface mount package.

■ PART NUMBER INFORMATION

SMC 2302 S - TR G

a	b	c	d	e
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a : Company name.

b : Product Serial number.

c : Package code S: SOT-23

d : Handling code TR: Tape&Reel

e : Green produce code G: *RoHS Compliant*

■ FEATURES

$V_{DS} = 20V, I_D = 5A$

$R_{DS(ON)}=30m\Omega(\text{Typ.}) @ V_{GS}=4.5V$

$R_{DS(ON)}=38m\Omega(\text{Typ.}) @ V_{GS}=2.5V$

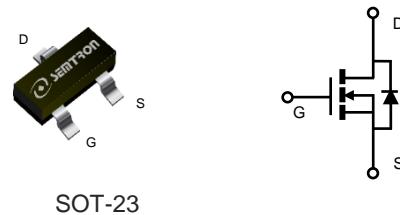
$R_{DS(ON)}=50m\Omega(\text{Typ.}) @ V_{GS}=1.8V$

- ◆ Fast switch
- ◆ 1.8V Low gate drive applications
- ◆ Improved dv/dt capability
- ◆ High power and current handling capability

■ APPLICATIONS

◆ Hand-Held Instruments

◆ Load Switch



SOT-23

■ ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 10	V
I_D	Continuous Drain Current $T_A=25^\circ C$	5	A
		4	A
I_{DM}	Pulsed Drain Current ^A	20	A
P_D	Power Dissipation ^B $T_A=25^\circ C$	1.3	W
		0.8	W
T_J	Operation Junction Temperature	-55/150	$^\circ C$
T_{STG}	Storage Temperature Range	-55/150	$^\circ C$

■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^B $t \leq 10s$		95	$^\circ C/W$
	Thermal Resistance Junction to Ambient ^{BC} Steady-State		130	

ELECTRICAL CHARACTERISTICS($T_A = 25^\circ\text{C}$ Unless otherwise noted)

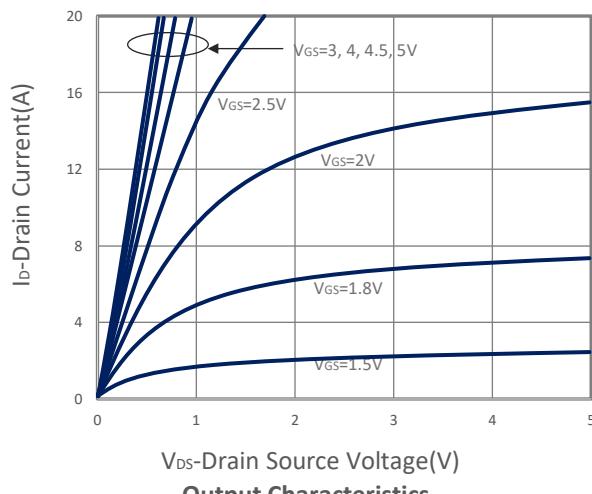
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
Static Parameters							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.4	0.6	1	V	
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 10\text{V}$			± 100	nA	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$			1	μA	
		$V_{DS}=16\text{V}, V_{GS}=0\text{V}, T_J=75^\circ\text{C}$			10		
$R_{DS(\text{ON})}$	Drain-source On-Resistance	$V_{GS}=4.5\text{V}, I_D=5\text{A}$		30	35	$\text{m}\Omega$	
		$V_{GS}=2.5\text{V}, I_D=3\text{A}$		38	45		
		$V_{GS}=1.8\text{V}, I_D=2\text{A}$		50	60		
G_f	Forward Transconductance	$V_{DS}=5\text{V}, I_D=4\text{A}$		4		S	
Diode Characteristics							
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.6	1	V	
I_S	Continuous Source Current				2.5	A	
Dynamic and Switching Parameters							
Q_g	Total Gate Charge	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}, I_D=5\text{A}$		5.7	8	nC	
Q_{gs}	Gate-Source Charge			0.8	1.1		
Q_{gd}	Gate-Drain Charge			1.5	2.1		
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		305		pF	
C_{oss}	Output Capacitance			52			
C_{rss}	Reverse Transfer Capacitance			43			
$t_{d(on)}$	Turn-On Time	$V_{DD}=10\text{V}, V_{GEN}=4.5\text{V}$ $R_G=6\Omega, I_D=1\text{A}$		3	6	nS	
t_r				7.8	15		
$t_{d(off)}$	Turn-Off Time			12	23		
t_f				5.4	10		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

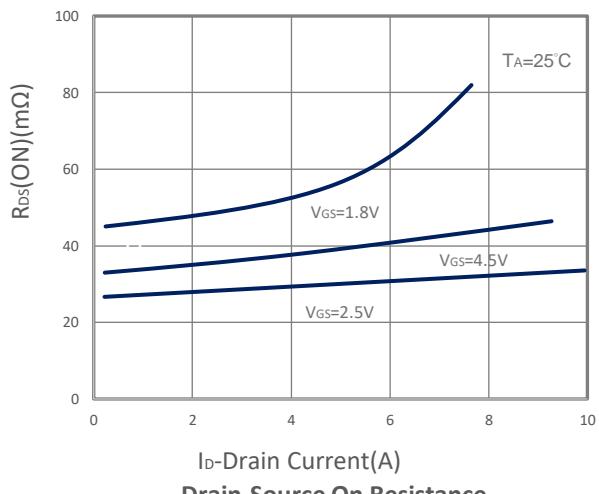
- A. Pulsed width limited by maximum junction temperature, $T_J(\text{MAX})=150^\circ\text{C}$.
- B. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board in a still air environment with maximum junction temperature $T_J(\text{MAX})=150^\circ\text{C}$ (initial temperature $T_A=25^\circ\text{C}$).
- C. $T_J(\text{MAX})=150^\circ\text{C}$, using junction-to-case thermal resistance ($R_{\theta JC}$) is more useful in additional heat sinking is used.

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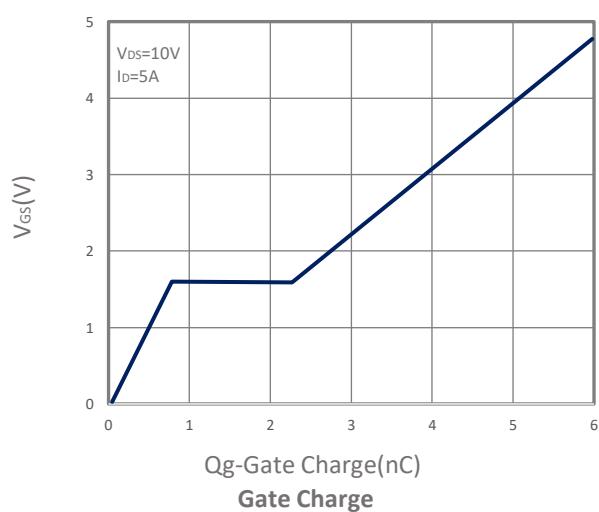
TYPICAL CHARACTERISTICS



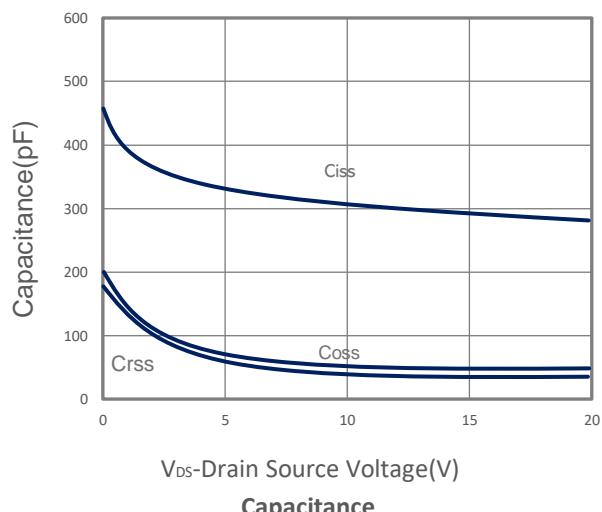
Output Characteristics



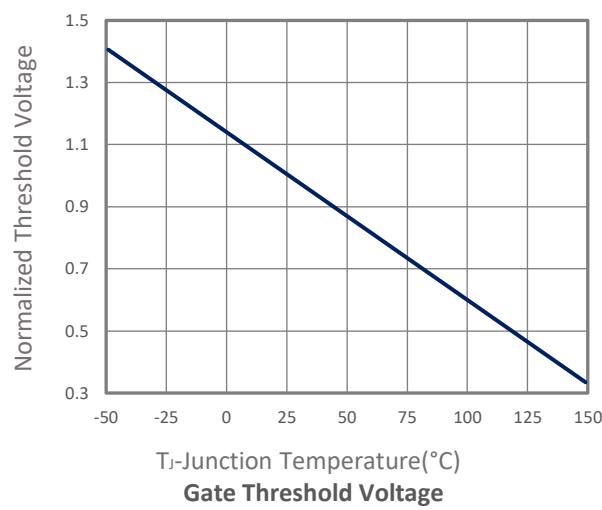
Drain-Source On Resistance



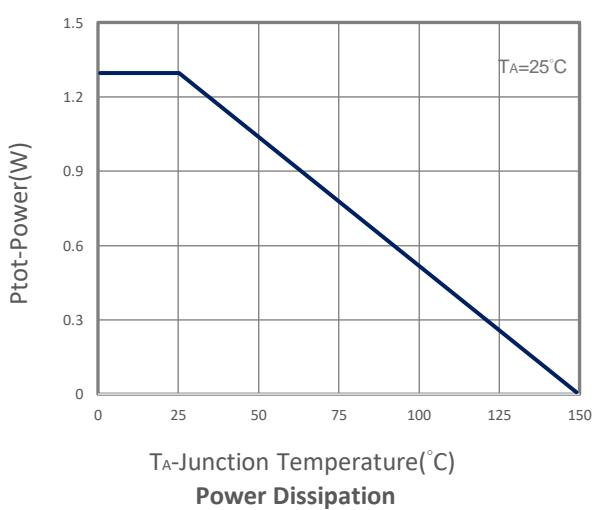
Gate Charge



Capacitance

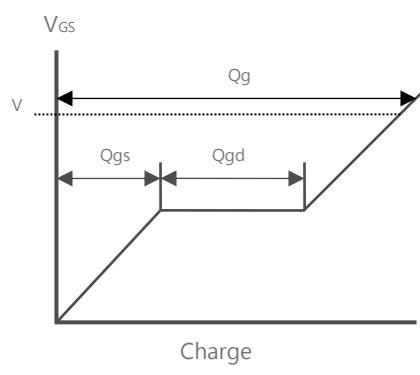
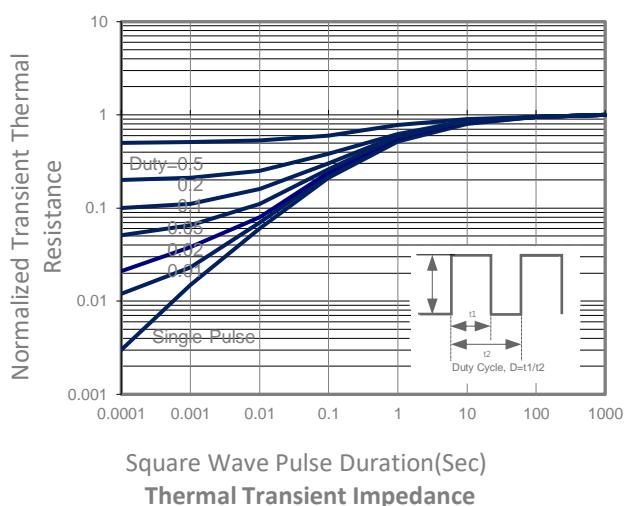
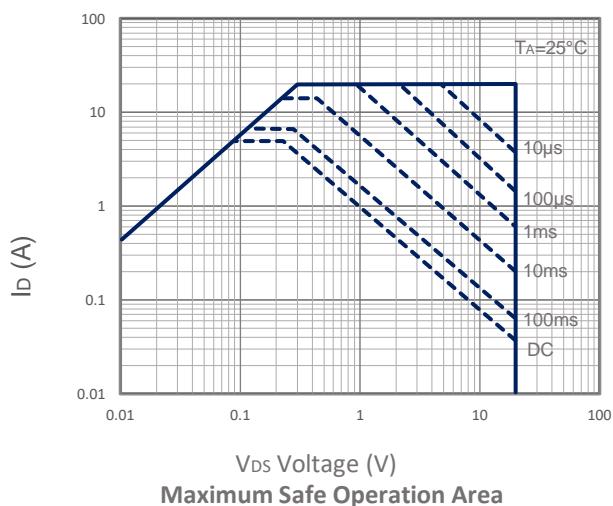
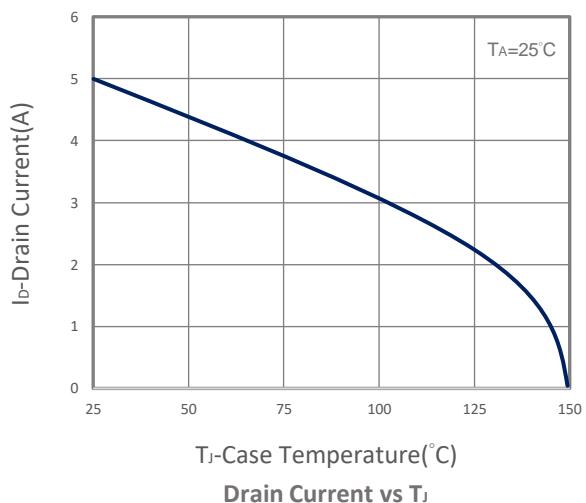
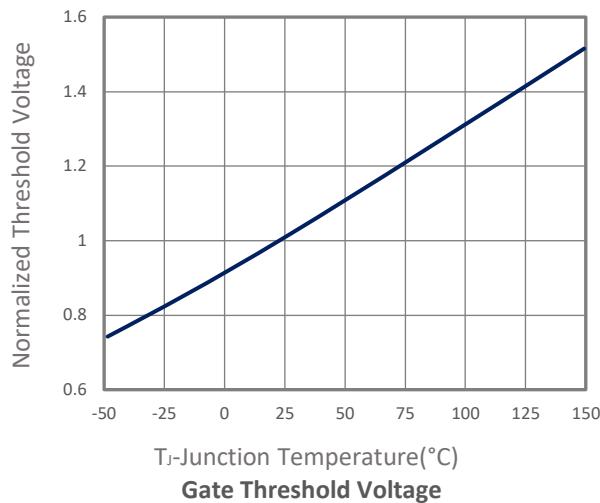


Gate Threshold Voltage

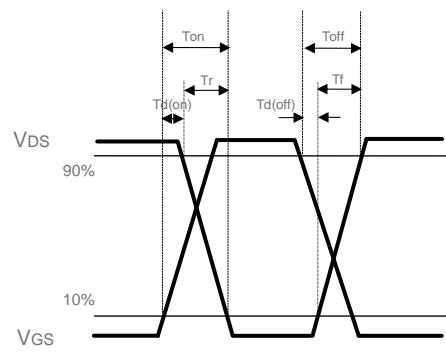


Power Dissipation

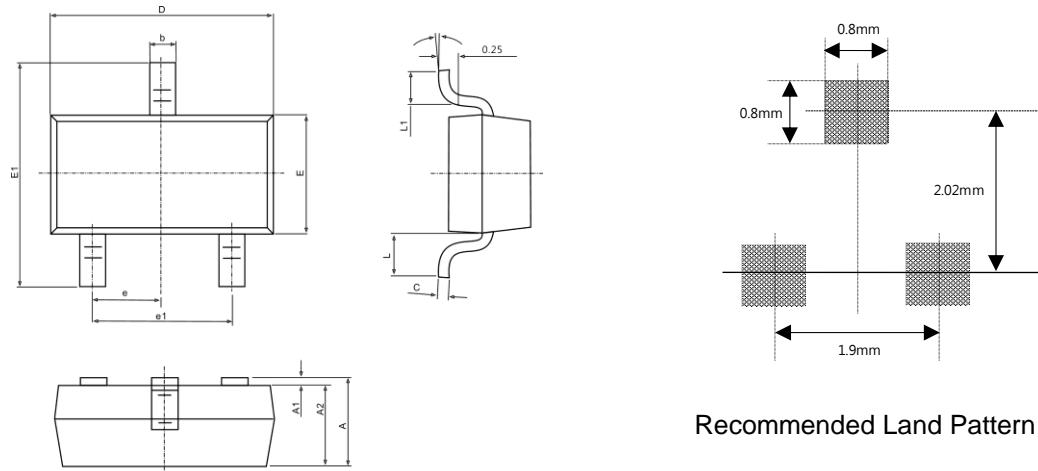
TYPICAL CHARACTERISTICS



Gate Charge Waveform



Switching Time Waveform

SOT-23 PACKAGE DIMENSIONS


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°